



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. LEAD COPLANARITY IS 0.003 INCH MAX.

SYMBOL	DIMENSION IN INCH			DIMENSION IN MM		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	.095	.102	.110	2.413	2.591	2.794
A1	.008	.012	.016	0.203	0.305	0.406
b	.008	-	.014	0.203	-	0.343
c	.005	-	.010	0.127	-	0.254
D	.720	.725	.730	18.288	18.415	18.542
E	.395	-	.420	10.033	-	10.668
E1	.291	.295	.299	7.391	7.493	7.595
e	.025 BASIC			0.635 BASIC		
h	.015	-	.025	0.381	-	0.635
L	.020	-	.040	0.508	-	1.016
L1	.010 BASIC			0.254 BASIC		
N	56					
REF	MO-118AB					



TITLE:
**POD for 56LD SSOP (300 MIL),
0.635MM PITCH**

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Page 1 of 2



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A	ECR-723	8/6/2008	RP	NEW RELEASE